

PCN# 20180622001.1

**Qualification of DMOS6 as an additional Wafer Fab Site option for select devices
Change Notification / Sample Request**

Date: June 25, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20180622001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC2564CRVMT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180622001.1	PCN Date:	Jun 25, 2018
Title:	Qualification of DMOS6 as an additional Wafer Fab Site option for select devices in C021 Technology		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Sep 25, 2018	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of DMOS6 as an additional Wafer Fab site option for the products listed in the product affected section of this document.

Current Wafer Fab Site	Process	Wafer Diameter
TSMC-F14	C021	300mm

Additional Fab Site	Process	Wafer Diameter
DMOS6	C021	300mm

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
TSMC-F14	T14	TWN	Tainan City

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS6	DM6	USA	Dallas

Sample product shipping label (not actual product label)

Product Affected Group:

CC2564CRVMR	CC2564CRVMT	CC2564CYFVR	CC2564CYFVT
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Qualification Report

Orca CC256x ROM C Product Qualification for QFN Fab: TSMC14 & TI – DMOS6
 Assembly Sites: Amkor K1 & Amkor P1 for QFN, Clark for WCSP

Approved 04/04/2018

Product Attributes

	Qual Device 1: BL6450QRVMR	Qual Device 2: BL6450QRVMR	Qual Device 3: BL6450QVRM	Qual Device 4: XCC2567YFVT
Assembly Site	AMKOR K1	AMKOR P1	AMKOR P1	Clark
Package Family	QFN	QFN	QFN	WCSP
Flammability Rating				
Wafer Fab Supplier	TSMC-F14	TSMC-F14	DMOS6	DMOS6
Wafer Fab Process	1218C021.M6	1218C021.M6	1218C021.M6	1218C021.M6

- QBS: Qual By Similarity
- Qual Device BL6450QRVMR is qualified at LEVEL3-260C
- Qual Device XCC2567YFVT is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device 1: BL6450QRVMR	Qual Device 2: BL6450QRVMR	Qual Device 3: BL6450QRVM	Qual Device 4: XCC2567YFVT
THB	Temperature and Humidity Bias, 85C/85%RH	1000 Hours	3/231/0	3/233/0	2/154/0	3/86/0
UHASt	Unbiased Humidity, 110C/85% RH	264 Hours	3/231/0	-	3/231/0	-
UHASt	Unbiased Humidity, 130C/85% RH	96 Hours	-	3/234/0	-	3/230/0
TC	Thermal Cycle, -55/125C	1000 Cycles	3/230/0	-	3/231/0	3/230/0
HTSL	High Temperature Storage Bake, 150C	1000 Hours	3/231/0	3/234/0	1/45/0	3/231/0
HTOL	Life Test, 125C	1000 Hours	3/230/0	-	3/231/0	-
WBS	Wire Bond Shear	(Cpk>1.67)	-	Pass	Pass	NA
WBP	Wire Bond Pull	(Cpk>1.67)	-	Pass	Pass	NA
PD	Physical Dimensions	(Cpk>1.67)	-	Pass	Pass	Pass
HBM	ESD-HBM	500V	1/3/0	-	1/3/0	1/3/0
CDM	ESD-CDM	250V	-	-	1/3/0	1/3/0
LU	Latch-up, High Temp	+/- 100 mA and 1.5 x Vmax @ max Tj	3/18/0	-	1/3/0	-
MQ	Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -65C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

This Quality and Reliability Report is provided strictly "AS IS", with all faults, and without any warranty, express or implied. All data relating to product performance under the conditions described herein are estimations only. Product information detailed in this Report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products.

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For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com